Performance Specification

Model	Marking	V_{max} (V dc)	I_{max} (A)	I_{hold} @25°C (A)	I_{trip} @25°C (A)	P_d Typ. (W)	Maximum Time To Trip Current (A)	Maximum Time To Trip Time (Sec)	Resistance $R_{i\ min}$ (Ω)	Resistance $R1_{max}$ (Ω)
K1206L025/24BR	R2	24.0	10	0.25	0.50	0.6	8.00	0.08	0.350	2.500

V max = Maximum operating voltage device can withstand without damage at rated current (Imax).

I max = Maximum fault current device can withstand without damage at rated voltage (V max).

I hold = Hold Current. Maximum current device will not trip in 25°C still air.

I trip = Trip Current. Minimum current at which the device will always trip in 25°C still air.

Pd = Power dissipation when device is in the tripped state in 25°C still air environment at rated voltage.

Ri min/max = Minimum/Maximum device resistance prior to tripping at 25°C.

R1max = Maximum device resistance is measured one hour post reflow.

CAUTION : Operation beyond the specified ratings may result in damage and possible arcing and flame.

Environmental Specifications

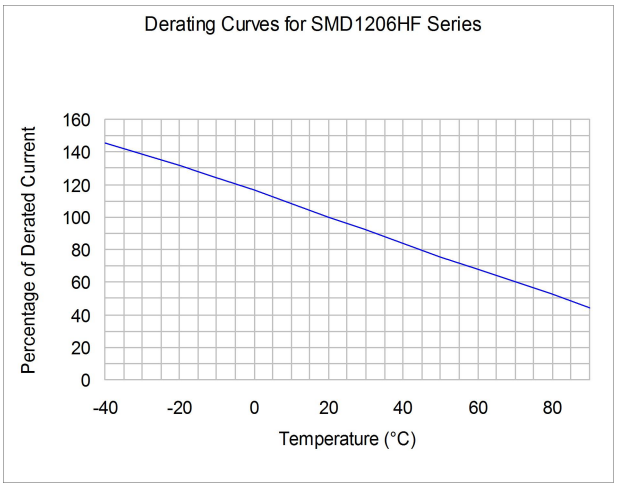
Test	Conditions	Resistance change
Passive aging	+85°C, 1000 hrs.	I HOLD/I TRIP PASS
Humidity aging	+85°C, 85% R.H. , 168 hours	I HOLD/I TRIP PASS
Thermal shock	+85°C to -40°C, 20 times	I HOLD/I TRIP PASS
Resistance to solvent	MIL-STD-202,Method 215	No change
Vibration	MIL-STD-202,Method 201	No change
Ambient operating conditions : - 40 °C to +85 °C		
Maximum surface temperature of the device in the tripped state is 125 °C		

Thermal Derading Chart

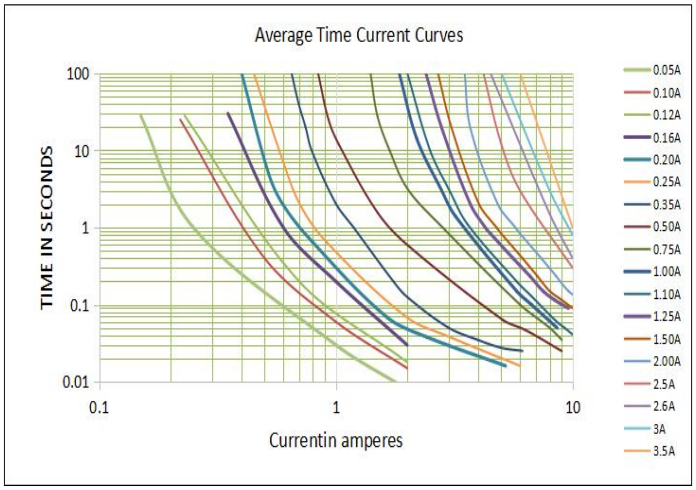
Recommended Hold Current(A) at Ambient Temperature(°C)

Model	Ambient Operation Temperature								
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
K1206L025/24BR	0.37	0.33	0.29	0.25	0.22	0.20	0.17	0.15	0.12

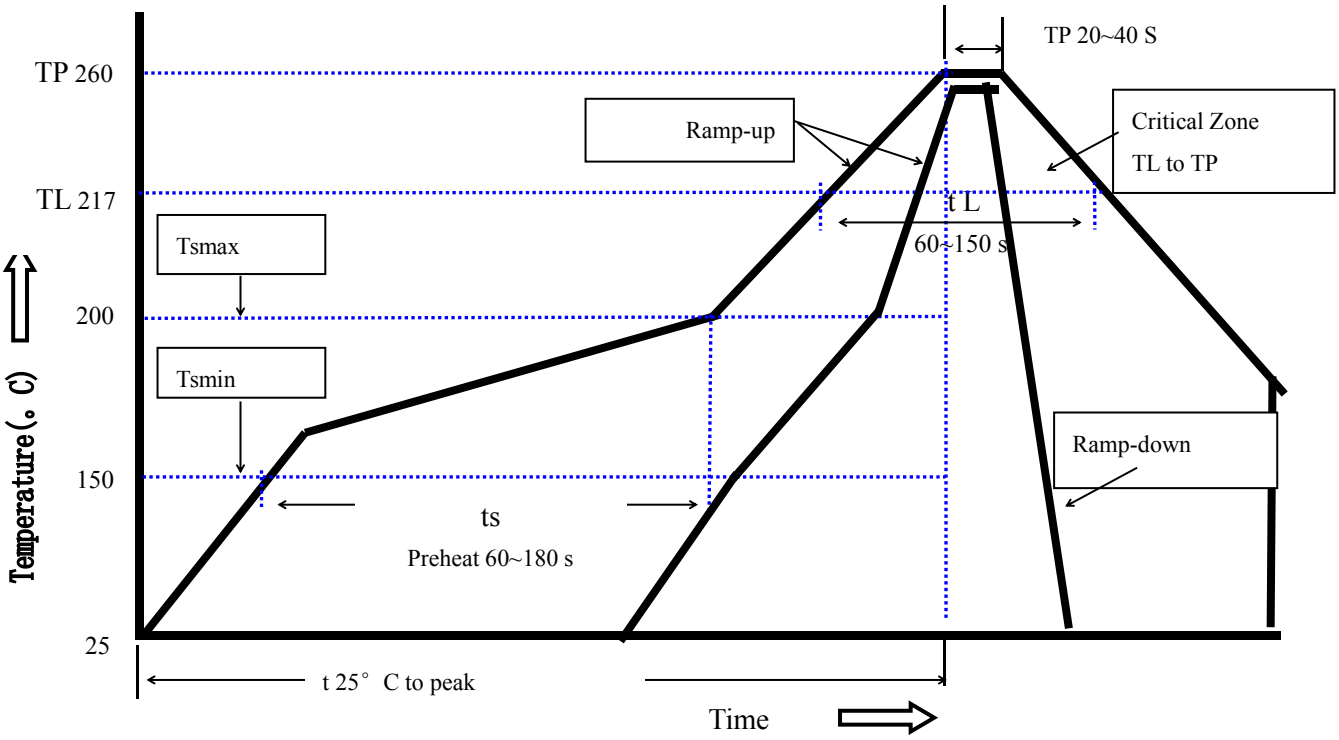
Thermal Derating Curve



Average Time-Current Curve



Soldering Parameters



Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate(Ts max to T p)	3℃/second mac.
Preheat	
-Temperature Min(Ts min)	150℃
-Temperature Max(Ts max)	200℃
-Time(Ts min to Ts max)	60~180 seconds
Time maintained above:	
-Temperature(TL)	217℃
-Time(tL)	60~150 seconds

Peak Temperature(Tp)	260℃
Ramp-Down Rate	6℃/second max.
Time 25℃ to Peak Temperature	8 minutes max
Storage Condition	0℃~30℃,30%~60%RH

Recommended reflow methods: IR, vapor phase oven, hot air oven, N2 environment for lead-free

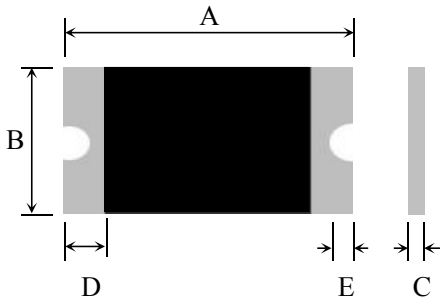
Recommended maximum paste thickness is 0.25mm

Devices can be cleaned using standard industry methods and solvents.

Note 1:All temperature refer to topside of the package, measured on the package body surface.

Note 2: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Physical Dimensions(mm.)



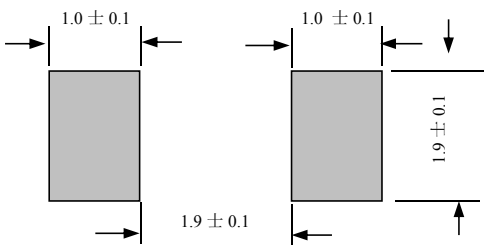
Model	A		B		C		D	E
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Min.
K1206L025/24BR	3.00	3.60	1.50	1.90	0.40	1.00	0.15	0.10

Termination Pad Characteristics

Terminal pad materials：Tin-plated Nickel-Copper

Terminal pad solder ability：Meets EIA specification RS186-9E and ANSI/J-STD-002 Category 3.

Recommended Pad Layout (mm.)



注：在此印锡面积条件下，推荐钢网厚度为≧0.12MM(钢网厚度不够要增大刷锡面积）

Packaging Quantity

Part Number	Quantity
K1206L025/24BR	4500 pcs/reel

Tape & reel packaging per EIA481-1